

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Wolfgang Hetzel et al.	Examiner:	Unknown
Serial No.:	10/577,173	Group Art Unit:	Unknown
Filed:	April 26, 2006	Docket:	I441.141.101 (formerly I431.156.101/FIN546PCT/US)
Title:	SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING SAME		

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**SECOND STATUS INQUIRY**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

An application for the above-identified patent application was filed on April 26, 2006.

We have **not received any type of communication** at all.

Kindly inform Applicant as to the status of this application.

Any inquiries may be directed to Applicant's attorney, Mark L. Gleason, at (612) 767-2503.

Respectfully submitted,  
Wolfgang Hetzel et al.,  
By their attorneys,

Dated: 06/16/2009  
MLG:cjs

/Mark L. Gleason/  
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